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TPQM6008K

60V N-Channel MOSFET

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General Features

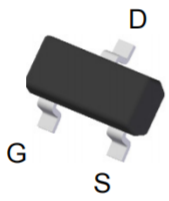
$V_{(BR)DSS}$	$R_{DS(on)}$MAX	I_D
60V	105mΩ@10V	3A
	125mΩ@4.5V	

Application

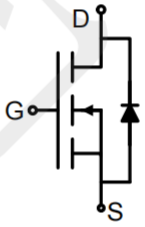
Load/Power Switching
Interfacing Switching
Battery Management for Ultra Small Portable
Logic Level Shift

Package and Pin Configuration

SOT23



Circuit diagram



Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	3	A
Pulsed Drain Current (note 1)	I_{DM}	10	A
Power Dissipation	P_D	0.35	W
Thermal Resistance from Junction to Ambient (note 2)	$R_{\theta JA}$	357	℃/W
Junction Temperature	T_J	150	℃
Storage Temperature	T_{STG}	-55~+150	℃

Electrical Characteristics (T_A=25℃unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D =250μA	60			V
Zero gate voltage drain current	I_{DSS}	V_{DS} =60V,V_{GS} = 0V			1	μA
Gate-body leakage current	I_{GSS}	V_{GS} =±20V, V_{DS} = 0V			±100	nA
Gate threshold voltage (note 3)	$V_{GS(th)}$	V_{DS} =V_{GS}, I_D =250μA	0.5		2	V
Drain-source on-resistance (note 3)	$R_{DS(on)}$	V_{GS} =10V, I_D =3A			105	mΩ
		V_{GS} =4.5V, I_D =3A			125	mΩ
Forward tranconductance (note 3)	g_{FS}	V_{DS} =15V, I_D =2A	1.4			S
Diode forward voltage (note 3)	V_{SD}	I_S=3A, V_{GS} = 0V			1.2	V
DYNAMIC CHARACTERISTICS (note 4)						
Input Capacitance	C_{iss}	V_{DS} =30V,V_{GS} =0V,f =1MHz		247		pF
Output Capacitance	C_{oss}			34		pF
Reverse Transfer Capacitance	C_{rss}			19.5		pF
SWITCHING CHARACTERISTICS (note 4)						
Turn-on delay time	$t_{d(on)}$	V_{GS}=10V,V_{DD}=30V, I_D=1.5A,R_{GEN}=1Ω		6		ns
Turn-on rise time	t_r			15		ns
Turn-off delay time	$t_{d(off)}$			15		ns
Turn-off fall time	t_f			10		ns
Total Gate Charge	Q_g	V_{DS} =30V,V_{GS} =4.5V,I_D =3A		6		nC
Gate-Source Charge	Q_{gs}			1		nC
Gate-Drain Charge	Q_{gd}			1.3		nC

Typical Electrical and Thermal Characteristics (Curves)

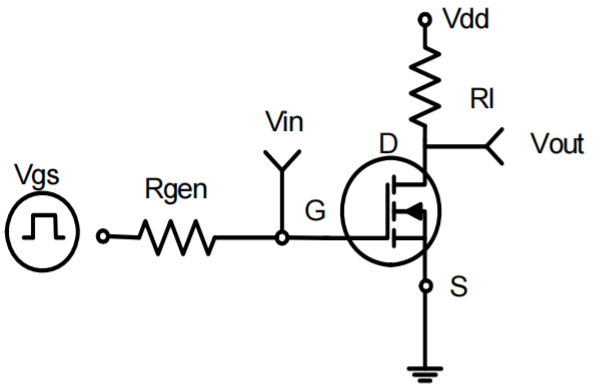


Figure 1:Switching Test Circuit

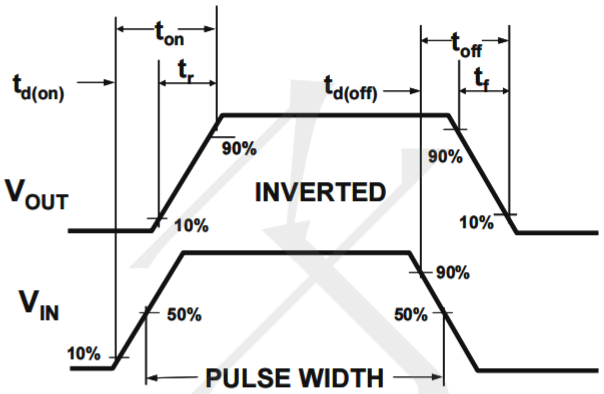


Figure 2:Switching Waveforms

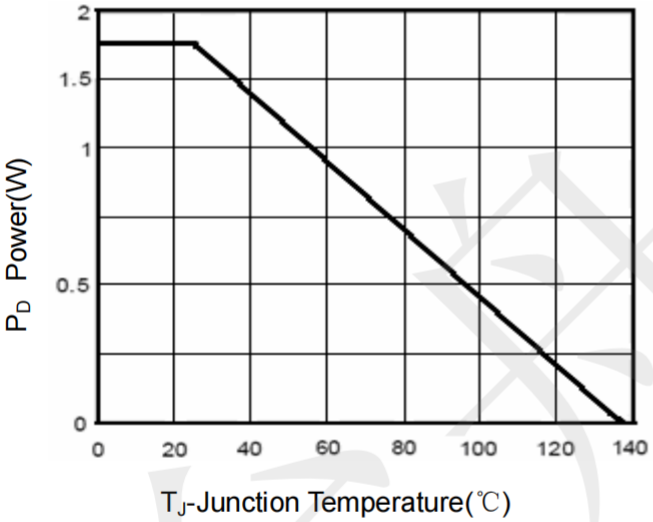


Figure 3 Power Dissipation

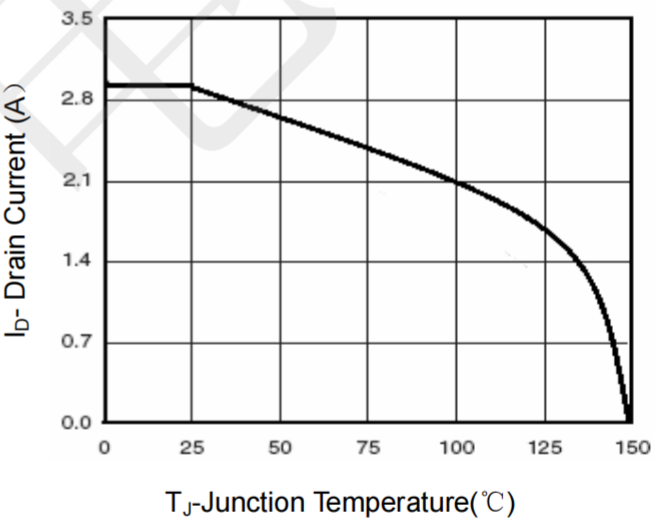


Figure 4 Drain Current

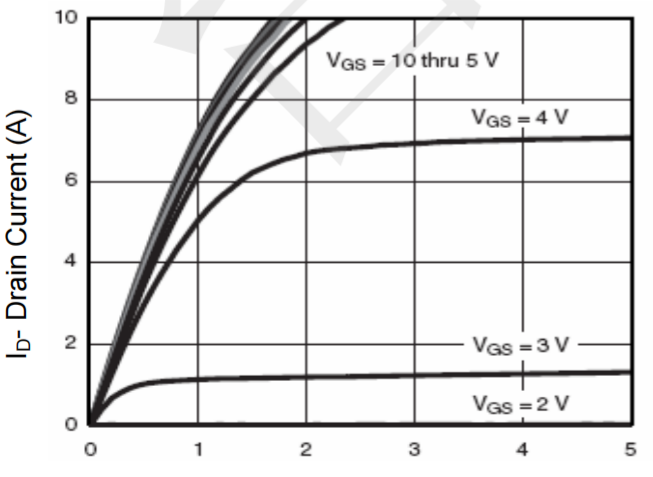


Figure 5 Output Characteristics

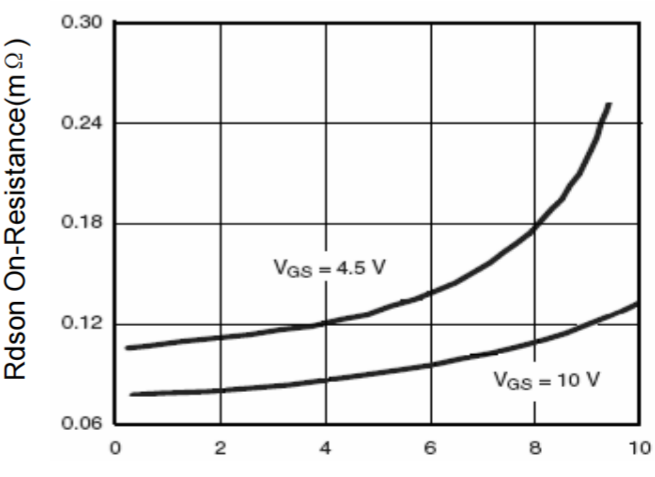


Figure 6 Drain-Source On-Resistance

Typical Electrical and Thermal Characteristics (Curves)

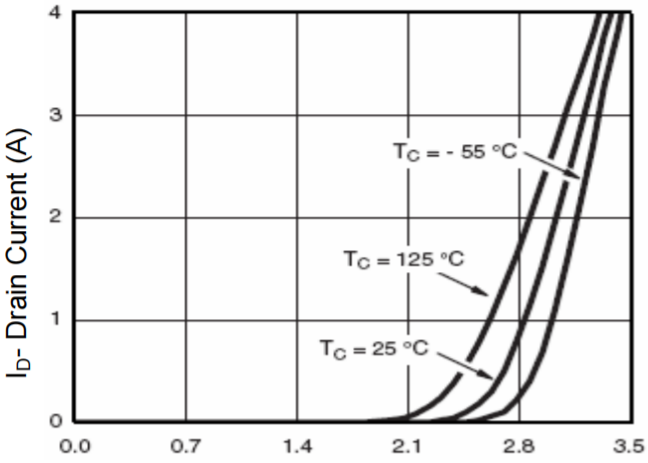


Figure 7 Transfer Characteristics

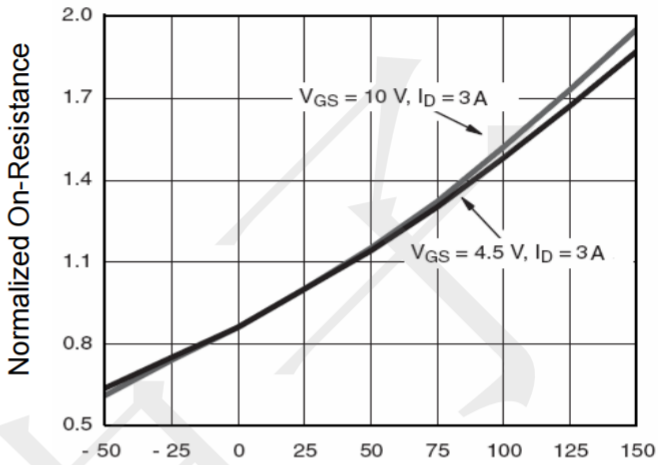


Figure 8 Drain-Source On-Resistance

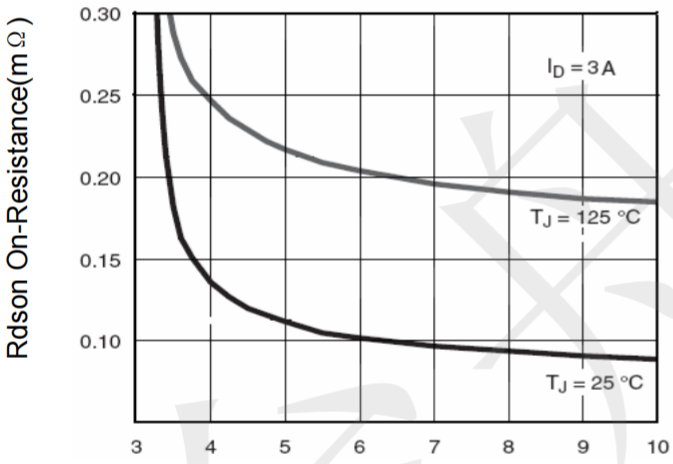


Figure 9 Rdson vs Vgs

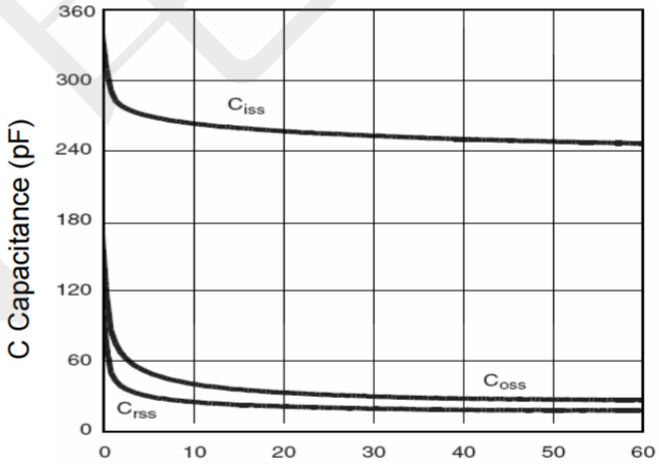


Figure 10 Capacitance vs Vds

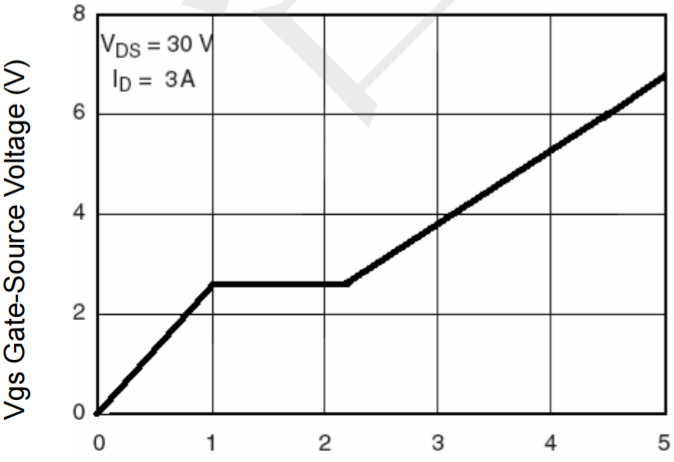


Figure 11 Gate Charge

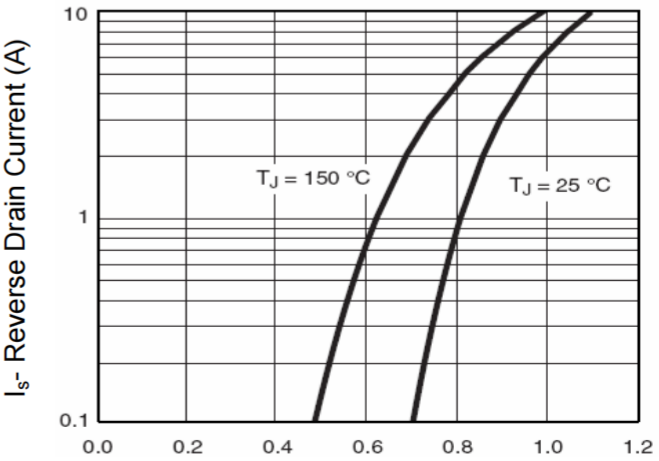


Figure 12 Source- Drain Diode Forward

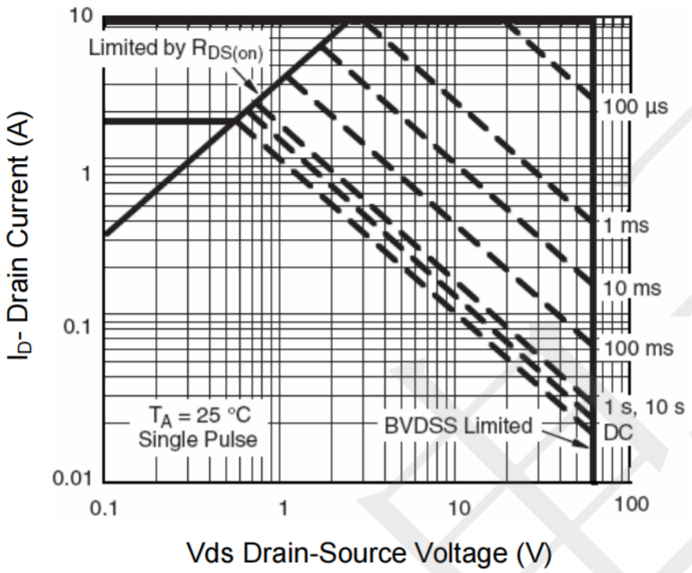


Figure 13 Safe Operation Area

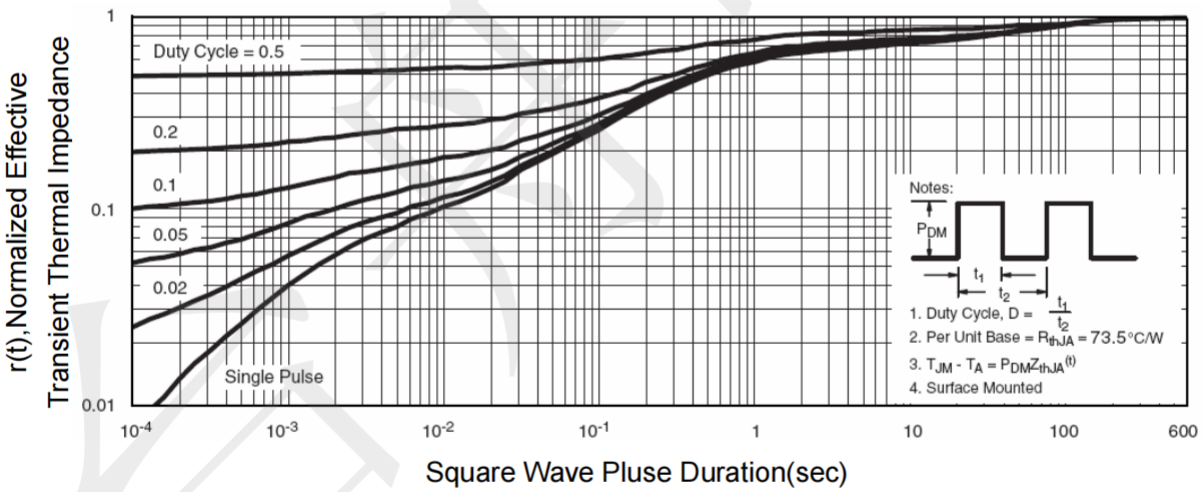
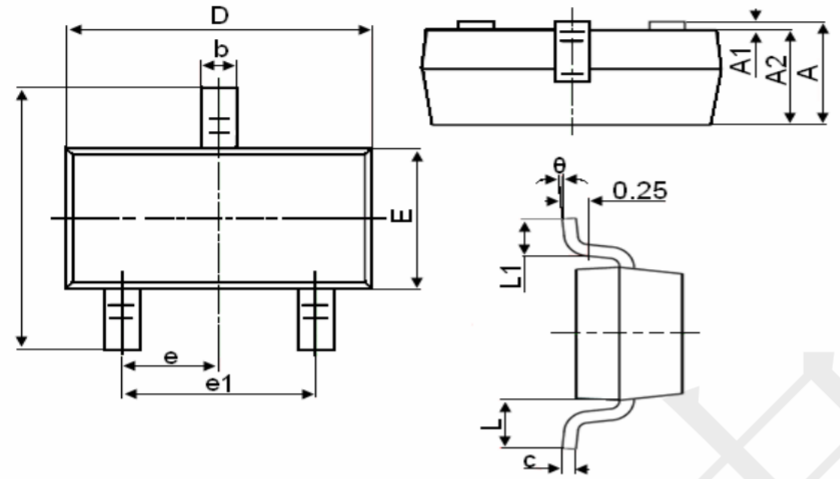


Figure 14 Normalized Maximum Transient Thermal Impedance

Package Outline Dimensions (SOT-23)



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°